Abstract—C\textsubscript{O}VER is an experiment which aims to detect the signature of gravitational waves from inflation by measuring the B-mode polarization of the cosmic microwave background. C\textsubscript{O}VER consists of three telescopes operating at 97, 150, and 220 GHz. The 97-GHz telescope has 160 feedhorns in its focal plane while the 150 and 220-GHz telescopes have 256 horns each. The horns are arranged in a hexagonal array and feed a polarimeter which uses fineline-coupled TES bolometers as detectors. To detect the two polarizations the 97-GHz telescope has 320 detectors while the 150 and 220-GHz telescopes have 512 detectors each. To achieve the target NEPs (1.5, 2.5, and 4.5 \times 10^{-17} \text{W}/\sqrt{\text{Hz}}) the detectors are cooled to 100 mK for the 97 and 150-GHz polarimeters and 230 mK for the 220-GHz polarimeter. Each detector is fabricated as a single chip to ensure a 100\% operational focal plane. The detectors are contained in linear modules made of copper which form split-block waveguides. The detector modules contain 16 or 20 detectors each for compatibility with the hexagonal arrays of horns in the telescopes’ focal planes. Each detector module contains a time-division SQUID multiplexer to read out the detectors. Further amplification of the multiplexed signals is provided by SQUID series arrays. The first prototype detectors for C\textsubscript{O}VER operate with a bath temperature of 230 mK and are used to validate the detector design as well as the polarimeter technology. We describe the design of the C\textsubscript{O}VER detectors, detector blocks, and readout, and present preliminary measurements of the prototype detectors’ performance.

I. INTRODUCTION

A. Scientific motivation

THOMSON scattering of primaeval radiation in the early Universe can lead to linear polarization[1] in the cosmic microwave background (CMB). The polarization depends on density fluctuations, and thus carries cosmological information which is complimentary to the well-studied temperature anisotropies of the CMB. The linear polarization may be decomposed into a curl-free part and a divergence-free part, denoted E- and B-mode respectively, by analogy with the electric field strength E and magnetic induction B. Linear density perturbations do not produce B-mode polarization, while tensor perturbations, as might be produced by gravitational waves, produce E- and B-mode polarization with similar amplitude[2], [3]. Thus, by measuring the B-mode polarization of the CMB with C\textsubscript{O}VER we hope to make an indirect detection of a background of primordial gravitational waves.

B. Overview of C\textsubscript{O}VER

The C\textsubscript{O}VER experiment is described in detail elsewhere[4]. C\textsubscript{O}VER consists of three telescopes observing at frequencies of 97, 150, and 220 GHz. The focal plane of each telescope will be populated by feed horns, each connected to a polarimeter. The polarimeter technology is yet to be determined. As part of the technology development program for C\textsubscript{O}VER we are constructing a Single Pixel Demonstrator. This instrument will contain six TES detectors, allowing us to evaluate different polarization technologies, as well as validating the detector design.

II. C\textsubscript{O}VER DETECTORS

A. Detector Requirements

For maximum sensitivity, we require that the detectors be background-limited, i.e. the contributions to the noise equivalent power (NEP) from the detectors and readout must be less than half of the photon noise from the sky:

\[ N\text{E}P_{\text{det}}^2 + N\text{E}P_{\text{read}}^2 < \frac{1}{4} N\text{E}P_{\text{photon}}^2 \]  

Once the detectors are background-limited the only way to improve the sensitivity is to increase the number of detectors. C\textsubscript{O}VER’s sensitivity requirements mean that we need 160 horns at 97 GHz and 256 each at 150 and 220 GHz. Because the polarimeter splits the power from each horn into two modes which must be measured independently, the number of detectors is twice this. We require a detector time constant of less than 1 ms. Also, the detectors must be able to absorb the power incident from the sky without saturation. This power is variable and depends on the weather. The power-handling
TABLE I
"CtOVER" DETECTOR REQUIREMENTS AT THE THREE OPERATING FREQUENCIES.

<table>
<thead>
<tr>
<th>Centre Frequency (GHz)</th>
<th>Band of Requirement (GHz)</th>
<th>Number of detectors</th>
<th>NEP Requirement (10^{-17} W/√Hz)</th>
<th>Power Handling (pW)</th>
</tr>
</thead>
<tbody>
<tr>
<td>97</td>
<td>82-112</td>
<td>320</td>
<td>1.5</td>
<td>6.7</td>
</tr>
<tr>
<td>150</td>
<td>127.5-172.5</td>
<td>512</td>
<td>2.5</td>
<td>11.5</td>
</tr>
<tr>
<td>220</td>
<td>195-255</td>
<td>512</td>
<td>4.5</td>
<td>18.8</td>
</tr>
</tbody>
</table>

The detector requirements are for the detectors to be able to operate for 75% of the time at the site. The detector requirements are summarized in Table I.

B. Detector Architecture

The current configuration has a single TES on each chip, fed by a single finline. There are two main reasons for going against the current trend towards large monolithic arrays. First, because the focal plane is populated by feedhorns, the waveguides coming from the polarimeter are on a pitch which is much larger than the size of the detectors. The horn diameters are 18.4, 12.77, and 8.4 mm at 97, 150, and 220 GHz, respectively. A monolithic array would have large inactive areas between active elements, increasing the number of wafers that would have to be processed, and hence the cost and manufacturing time. Second, because high sensitivity is essential for achieving "CtOVER"'s science goals, we decided to fabricate each detector on a single chip so that good devices could be selected to guarantee that all the detectors in each focal plane are working. The chips are micromachined and diced by deep reactive ion etching (DRIE) at the Scottish Microelectronics Centre.

C. R.F. Design

To reach background-limited sensitivity "CtOVER"’s bolometers must have a high absorption efficiency. Power is coupled from the waveguide to the TES planar circuit using an antipodal finline taper consisting of two superconducting fins of Nb separated by 400 nm of SiO₂ [5], [6] (see Fig. 1). The lower Nb layer is 250 nm thick. The upper layer is 500 nm thick to ensure reliable lift-off patterning with the step over the oxide layer. The whole structure is deposited on one side of a 225-μm silicon substrate. Before the fins overlap, the thickness of the SiO is much less than that of the silicon and the structure behaves as a unilateral finline. As the fins overlap, the structure starts to behave like a parallel-plate waveguide with an effective width equal to the overlap region. When the width of the overlap region becomes large enough for fringing effects to be negligible, a transition to a microstrip mode has been performed. The microstrip is then tapered to the required width. "CtOVER" uses a 3-μm Nb microstrip with a characteristic impedance of 20 Ω to deliver power to the TES.

The detector chip's 225-μm silicon substrate loads the waveguide in which it sits, changing the waveguide impedance. To prevent reflections the chip has a tapered end which provides a gradual impedance transition. The prototype detectors for the Single Pixel Demonstrator sit in a WR-10 waveguide and have a taper angle of 40°. This angle was chosen based on finite-element electromagnetic modelling.

D. Bolometer Design

"CtOVER"'s bolometers are low-stress silicon nitride islands suspended on four legs (see Fig. 2). The nitride is 0.5 μm thick. The thermal conductance to the thermal bath is controlled by the four nitride legs. The microstrip carrying power from the finline to the bolometer is terminated by a 20-Ω Au/Cu resistor which dissipates the incoming power as heat that the superconducting transition edge sensor (TES) can detect. A shunt resistor in parallel with the TES ensures that it is voltage biased so that it operates in the regime of strong negative electrothermal feedback [7]. For example, if the temperature drops, so does the resistance of the TES. Since it is biased at constant voltage, this means that the current, and hence the Joule power, will increase, heating up the TES. Conversely, if the temperature increases the resistance will increase, reducing the current, and thus the Joule heating. This means that the TES operates at a bias point that is in a stable equilibrium. Thus, the TES is self-biasing. There is no need for a temperature controller to ensure that it remains at the correct bias point. Also, the electrothermal feedback cancels out temperature fluctuations which has the effect of suppressing the Johnson noise.

The TES films in "CtOVER" are Mo/Cu proximity-effect bilayers. The transitions of the bilayers can be made as sharp as 1–2 mK for high sensitivity. The sensitivity of the TES...
A. Readout

Given the large number of detectors in this instrument (320 at 97 GHz and 512 each at 150 and 220 GHz) some form of multiplexing is needed to have a manageable number of wires from room temperature. We use 1 x 32 time-domain SQUID multiplexers[9], [10] fabricated by the National Institute of Standards and Technology. All the multiplexer chips in each of C/COVER’s three telescopes share address lines, significantly reducing the number of wires needed to room temperature. The 1 x 32 multiplexer chip allows us to cover each region with linear detector blocks stacked on top of each other with an offset to match the hexagonal horn pitch. The orientation of one of these detector blocks is shown by a dark rectangle in each of the three regions. The main advantage of this arrangement is that it allows us to use identical detector blocks to cover a focal plane, reducing cost and complexity. A simplified view of a detector block holding four detectors is shown in Fig. 5. The feeding horns are arranged in a hexagonal array. However, the 1 x 32 multiplexer chips are more naturally to a planar configuration where we have up to 16 horns in a row. We therefore had to come up with a compromise arrangement which would allow us to tile the focal plane efficiently. As shown in Fig. 5 we split the 97-GHz focal plane into three regions. Clockwise from upper right these are a 7 x 7-horn parallelogram, an 8 x 7-horn parallelogram, and an 8 x 8-horn parallelogram. The two waveguides corresponding to each horn are arranged so that they are all parallel within one of these regions. This allows us to cover each region with linear detector blocks stacked on top of each other with an offset to match the hexagonal horn pitch. The orientation of one of these detector blocks is shown by a dark rectangle in each of the three regions. The main advantage of this arrangement is that it allows us to use identical detector blocks to cover a focal plane, reducing cost and complexity. The 97-GHz focal plane needs 22 detector blocks to cover it. The scheme for covering the 150- and 220-GHz focal planes is similar, except that the horns are arranged in a hexagon with a side of ten horns. This means that there are 28 detector blocks, each containing 20 detectors and one 1 x 32 multiplexer chip. This scheme has the apparent disadvantage that we are using multiplexer chips by a factor of up to two, increasing the number needed. However, because we are not using all of the first-stage SQUIDs on a multiplexer chip, we can connect the detectors to those SQUIDs that have the most similar critical currents. This optimizes the first-stage SQUID biasing, reducing the noise contribution from this stage of the readout. Reducing the number of detectors multiplexed by each multiplexer chip also reduces the aliased readout noise, improving the NEP. Another advantage of under-using the multiplexer chips is that we can use chips where not all the first-stage SQUIDs are functioning, reducing the cost per chip.

B. Populating the Focal Plane

The feeding horns are arranged in a hexagonal array. However, the 1 x 32 multiplexer chips are more naturally to a planar configuration where we have up to 16 horns in a row. We therefore had to come up with a compromise arrangement which would allow us to tile the focal plane efficiently. As shown in Fig. 5 we split the 97-GHz focal plane into three regions. Clockwise from upper right these are a 7 x 7-horn parallelogram, an 8 x 7-horn parallelogram, and an 8 x 8-horn parallelogram. The two waveguides corresponding to each horn are arranged so that they are all parallel within one of these regions. This allows us to cover each region with linear detector blocks stacked on top of each other with an offset to match the hexagonal horn pitch. The orientation of one of these detector blocks is shown by a dark rectangle in each of the three regions. The main advantage of this arrangement is that it allows us to use identical detector blocks to cover a focal plane, reducing cost and complexity. The 97-GHz focal plane needs 22 detector blocks to cover it. The scheme for covering the 150- and 220-GHz focal planes is similar, except that the horns are arranged in a hexagon with a side of ten horns. This means that there are 28 detector blocks, each containing 20 detectors and one 1 x 32 multiplexer chip. This scheme has the apparent disadvantage that we are using multiplexer chips by a factor of up to two, increasing the number needed. However, because we are not using all of the first-stage SQUIDs on a multiplexer chip, we can connect the detectors to those SQUIDs that have the most similar critical currents. This optimizes the first-stage SQUID biasing, reducing the noise contribution from this stage of the readout. Reducing the number of detectors multiplexed by each multiplexer chip also reduces the aliased readout noise, improving the NEP. Another advantage of under-using the multiplexer chips is that we can use chips where not all the first-stage SQUIDs are functioning, reducing the cost per chip.

C. Detector Block

The detector block comes in two halves, upper and lower. When these are put together they form split-block waveguides, into which the finlines protrude. The edges of the finlines stick into shallow slots in the sides of the waveguides for grounding. The serrations on the edges of the finlines (see Fig. 1) are there to prevent unwanted modes from propagating. A simplified view of a detector block holding four detectors is shown in Fig. 6.

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III. DETECTOR READOUT AND PACKAGING

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We have developed a process that allows us to mass-produce finline-coupled TES bolometers. This is the first time TES detectors have been mass-produced in the United Kingdom. We have produced prototype detectors for COVER and found that the TES films are of high quality, making for sensitive detectors. More development of the thermal design is needed to achieve the required power handling. We expect to measure the R.F. response of these detectors in the near future, demonstrating the operation of a finline transition on a silicon substrate for the first time.

ACKNOWLEDGMENT

The authors would like to thank Andrew Bunting at the Scottish Microelectronics Centre of the University of Edinburgh for carrying out the DRIE and for his helpful advice.

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